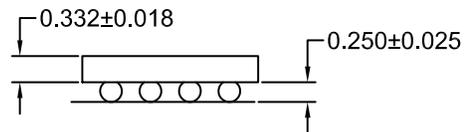
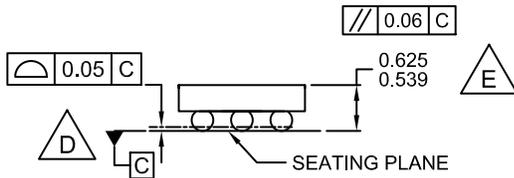
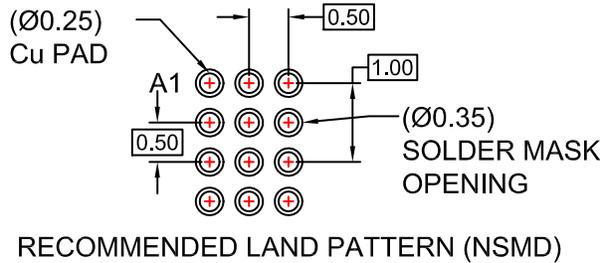
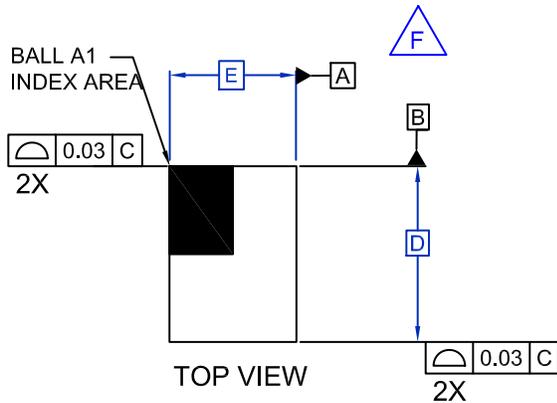
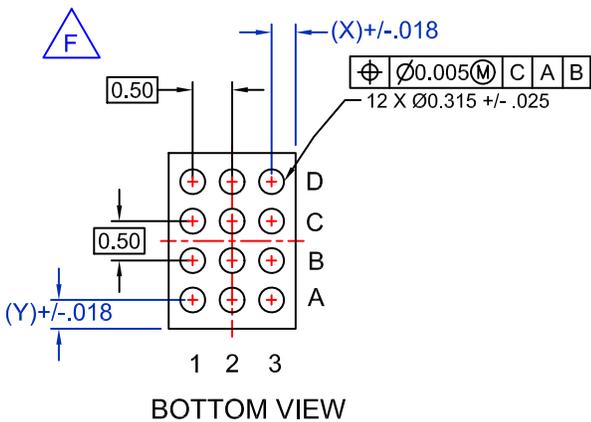


**WLCSP12 2.2x1.43x0.582**  
CASE 567PX  
ISSUE O

DATE 31 OCT 2016



**SIDE VIEWS**



**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 38 MICRONS (539-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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<b>DESCRIPTION:</b>	<b>WLCSP12 2.2x1.43x0.582</b>	<b>PAGE 1 OF 1</b>

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